

ABSTRACT OF THE DISCLOSURE

A miniaturized microwave circuit. The novel circuit includes a first substrate, a first ground plate disposed on a bottom surface of the first substrate, a second
5 substrate attached to a top surface of the first substrate and adapted to cover a portion of the first substrate, a second ground plate disposed on a top surface of the second substrate, a pattern of metallization disposed between the first and second substrates to form a stripline circuit, one or more ground paths disposed on the top surface of the first substrate and including a plurality of vias connected to the first ground plate, and
10 one or more openings cut into the second substrate and second ground plate, wherein each opening follows and is aligned over a portion of a ground path and is filled in with conducting material, such that the second ground plate is connected to the first ground plate.

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